Specification for Approval

Date: 2014/9/18

Halogen-free Pb-free Certificate of Green Partner

Customer : Qisda

TAI-TECH P/N: HPB2012ZF-300T50

CUSTOMER P/N: 6H.30060.0N1

DESCRIPTION:

QUANTITY: pcs

REMARK:		
Customer Approval Feedback		

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TAI-TECH Advanced Electronics Co., Ltd

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High Current Ferrite Chip Bead(Lead Free) HPB2012ZF-300T50

ECN HISTORY LIST

REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	13/06/06	變更可靠度條件	楊祥忠	羅培君	張嘉玲
2.0	14/01/24	變更電鍍錫層厚度 3.0um min.=>3.5um min.	楊祥忠	羅培君	張嘉玲
3.0	14/08/01	變更 Reflow 圖示	楊祥忠	羅培君	張嘉玲
3.1	14/08/01	修正包裝帶尺寸	楊祥忠	羅培君	張嘉玲
備註					

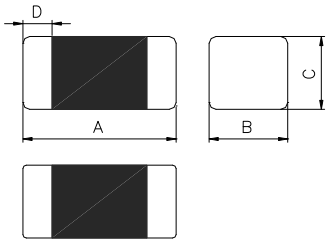
High Current Ferrite Chip Bead(Lead Free) HPB2012ZF-300T50

1.Features

1. Monolithic inorganic material construction.
2. Closed magnetic circuit avoids crosstalk.
3. Suitable for reflow soldering.
4. Shapes and dimensions follow E.I.A. spec.
5. Available in various sizes.
6. Excellent solder ability and heat resistance.
7. High reliability.
8. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
9. Low DC resistance structure of electrode to prevent wasteful electric power consumption.

Halogen-free Pb-free Certificate of Green Partner

2.Dimensions



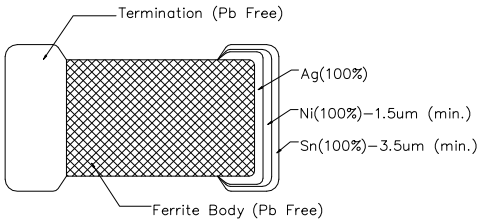
Chip Size	
A	2.00±0.20
B	1.25±0.20
C	0.85±0.20
D	0.50±0.30

Units: mm

3.Part Numbering

HPB	2012	ZF	-	300	T	50
A	B	C		D	E	F

A: Series
B: Dimension L x W
C: Material Lead Free Material
D: Impedance 300=30Ω
E: Packaging T=Taping and Reel, B=Bulk(Bags)
F: Rated Current 50=5000mA

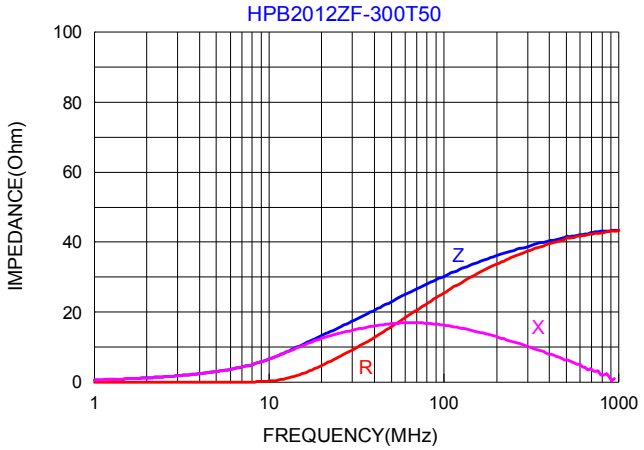


4.Specification

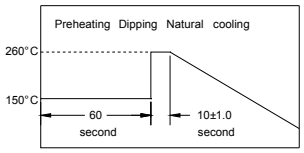
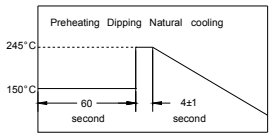
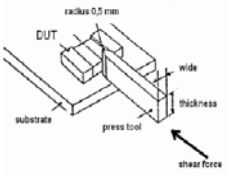
Tai-Tech Part Number	Impedance (Ω)	Test Frequency (Hz)	DC Resistance (Ω) max.	Rated Current (mA) max.
HPB2012ZF-300T50	30±25%	60mV/100M	0.01	5000

● Rated current: based on temperature rise test

■ Impedance-Frequency Characteristics



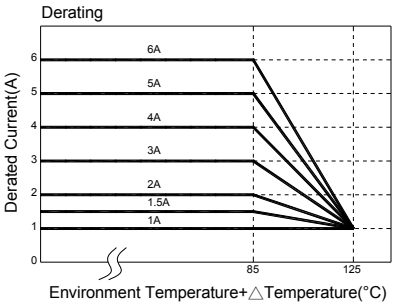
5. Reliability and Test Condition

Item	Performance									Test Condition
Series No.	FCB	FCM	HCB	GHB	FCA	FCI	FHI	FCH	HCI	--
Operating Temperature	-40~+125℃ (Including self-temperature rise)					-40~+105℃ (Including self-temperature rise)				--
Transportation Storage Temperature	-40~+125℃ (on board)					-40~+105℃ (on board)				For long storage conditions, please see the Application Notice
Impedance (Z)	Refer to standard electrical characteristics list									Agilent4291
Inductance (Ls)										Agilent E4991
Q Factor										Agilent4287
DC Resistance										Agilent16192 / Agilent 4338
Rated Current										DC Power Supply Over Rated Current requirements, there will be some risk
Temperature Rise Test	Rated Current < 1A ΔT 20℃Max Rated Current ≧ 1A ΔT 40℃Max									1. Applied the allowed DC current. 2. Temperature measured by digital surface thermometer.
Resistance to Soldering Heat	Appearance：No damage. Impedance：within±15% of initial value Inductance：within±10% of initial value Q：Shall not exceed the specification value. RDC：within ±15% of initial value and shall not exceed the specification value									Preheat: 150℃,60sec. Solder: Sn99.5%-Cu0.5% Solder temperature: 260±5℃ Flux for lead free: Rosin. 9.5% Temperature ramp/immersion and immersion rate: 25±6 mm/s Dip time: 10±1sec. Depth: completely cover the termination. 
Solderability	More than 95% of the terminal electrode should be covered with solder. 									Preheat: 150℃,60sec. Solder: Sn99.5%-Cu0.5% Solder temperature: 245±5℃ Flux for lead free: Rosin. 9.5% Depth: completely cover the termination. Dip time: 4±1sec.
Terminal strength	Appearance：No damage. Impedance：within±15% of initial value Inductance：within±10% of initial value Q：Shall not exceed the specification value. RDC：within ±15% of initial value and shall not exceed the specification value 									Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Component mounted on a PCB apply a force (>0805:1kg <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to shock the component being tested.
Bending	Appearance：No damage. Impedance：within±10% of initial value Inductance：within±10% of initial value Q：Shall not exceed the specification value. RDC：within ±15% of initial value and shall not exceed the specification value									Shall be mounted on a FR4 substrate of the following dimensions:>=0805:40x100x1.2mm <0805:40x100x0.8mm Bending depth:>=0805:1.2mm <0805:0.8mm Duration of 10 sec for a min.
Vibration Test	Appearance：No damage. Impedance：within±15% of initial value Inductance：within±10% of initial value Q：Shall not exceed the specification value. RDC：within ±15% of initial value and shall not exceed the specification value									Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Oscillation Frequency: 10～2K～10Hz for 20 minutes Equipment： Vibration checker Total Amplitude:1.52mm±10% Testing Time：12 hours(20 minutes, 12 cycles each of 3 orientations)。
Shock	Appearance：No damage. Impedance：within±15% of initial value Inductance：within±10% of initial value Q：Shall not exceed the specification value. RDC：within ±15% of initial value and shall not exceed the specification value									Test condition: Type / Peak Value (g's) / Normal duration (D) (ms) / Wave form / Velocity change (Vi)ft/sec SMD / 1,500 / 0.5 / Half-sine / 15.4 Lead / 100 / 6 / Half-sine / 12.3

Item	Performance	Test Condition
Life test	Appearance: no damage. Impedance: within±15%of initial value. Inductance: within±10%of initial value. Q：Shall not exceed the specification value. RDC：within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature: 125±2℃(bead), 85±2℃(inductor) Applied current: rated current. Duration: 1000±12hrs. Measured at room temperature after placing for 24±2 hrs.
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Humidity: 85±2%R.H. Temperature: 85±2℃. Duration: 1000hrs Min. with 100% rated current. Measured at room temperature after placing for 24±2 hrs.
Thermal shock	Appearance: no damage. Impedance: within±15%of initial value. Inductance: within±10%of initial value. Q：Shall not exceed the specification value. RDC：within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Condition for 1 cycle Step1: -40±2℃ 30±5 min. Step2: 25±2℃ ≦0.5min Step3: +105±2℃ 30±5min. Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs.
Insulation Resistance	IR>1GΩ	Chip Inductor Only Test Voltage:100±10%V for 30Sec.

****Derating Curve**

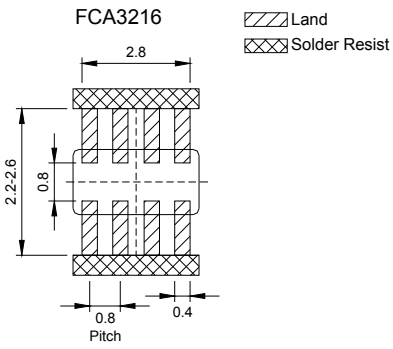
For the ferrite chip bead which withstanding current over 1.5A, as the operating temperature over 85℃, the derating current information is necessary to consider with. For the detail derating of current, please refer to the Derated Current vs. Operating Temperature curve.

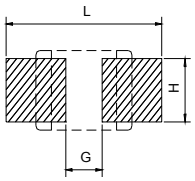


6.Soldering and Mounting

6-1. Recommended PC Board Pattern

Chip Size						Land Patterns For Reflow Soldering		
Series	**Type**	**A(mm)**	**B(mm)**	**C(mm)**	**D(mm)**	**L(mm)**	**G(mm)**	**H(mm)**
FCB	0603	0.6±0.03	0.30±0.03	0.30±0.03	0.15±0.05	0.80	0.30	0.30
FCM	1005	1.0±0.10	0.50±0.10	0.50±0.10	0.25±0.10	1.50	0.40	0.55
HCB	1608	1.6±0.15	0.80±0.15	0.80±0.15	0.30±0.20	2.60	0.60	0.80
GHB	2012	2.0±0.20	1.25±0.20	0.85±0.20	0.50±0.30	3.00	1.00	1.00
FCI		2.0±0.20	1.25±0.20	1.25±0.20	0.50±0.30			
FHI	3216	3.2±0.20	1.60±0.20	1.10±0.20	0.50±0.30	4.40	2.20	1.40
FCH	3225	3.2±0.20	2.50±0.20	1.30±0.20	0.50±0.30	4.40	2.20	3.40
HCI	4516	4.5±0.20	1.60±0.20	1.60±0.20	0.50±0.30	5.70	2.70	1.40
	4532	4.5±0.20	3.20±0.20	1.50±0.20	0.50±0.30	5.90	2.57	4.22





PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

6-2. Soldering

Mildly activated rosin fluxes are preferred. The terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

Note.

If wave soldering is used ,there will be some risk.

Re-flow soldering temperatures below 240 degrees, there will be non-wetting risk

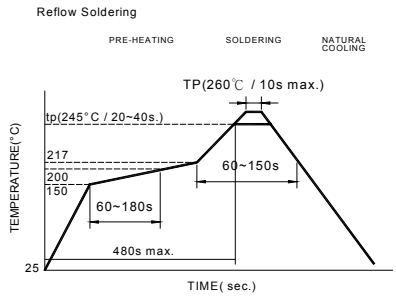
6-2.1 Lead Free Solder re-flow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. (Refered to J-STD-020C)

6-2.2 Soldering Iron:

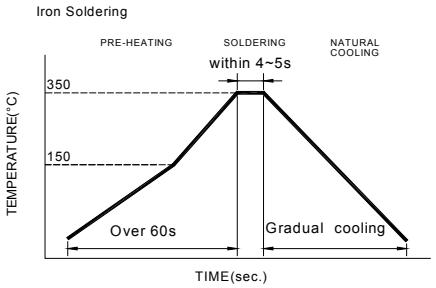
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. If a soldering iron must be employed the following precautions are recommended. for Iron Soldering in Figure 2.

- Preheat circuit and products to 150℃
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 350℃ tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.



Reflow times: 3 times max

Fig.1



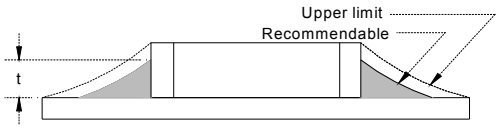
Iron Soldering times：1 times max

Fig.2

6-2.3 Solder Volume:

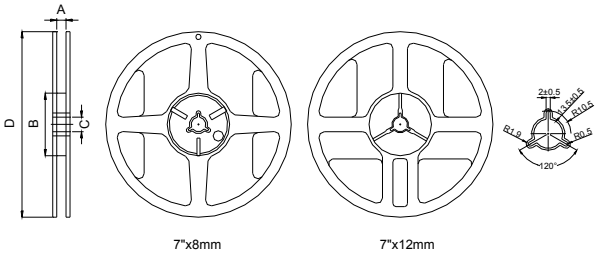
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:

Minimum fillet height = soldering thickness + 25% product height



7.Packaging Information

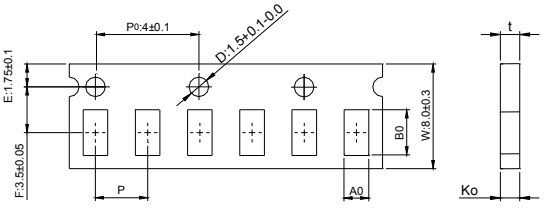
7-1. Reel Dimension



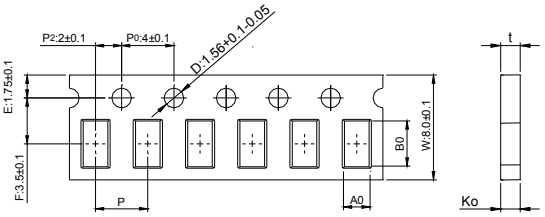
Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2

7-2.1 Tape Dimension / 8mm

■Material of taping is paper

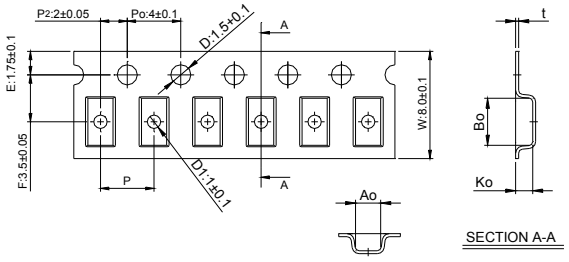


Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
060303	0.68±0.05	0.38±0.05	0.50max	2.0±0.05	0.50max
100505	1.12±0.03	0.62±0.03	0.60±0.03	2.0±0.05	0.60±0.03



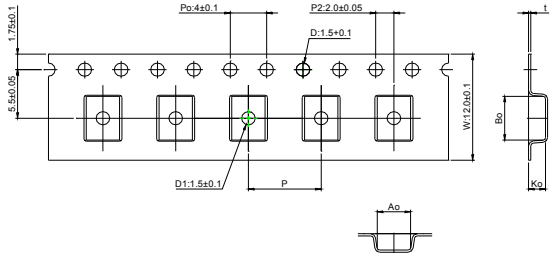
Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
160808	1.80±0.05	0.95±0.05	0.95±0.05	4.0±0.10	0.95±0.05
201209	2.10±0.05	1.30±0.05	0.95±0.05	4.0±0.10	0.95±0.05

■Material of taping is plastic



Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
201212	2.10±0.10	1.28±0.10	1.28±0.10	4.0±0.10	0.22±0.05	1.0±0.10
321611	3.35±0.10	1.75±0.10	1.25±0.10	4.0±0.10	0.23±0.05	1.0±0.10
322513	3.42±0.10	2.77±0.10	1.55±0.10	4.0±0.10	0.22±0.05	1.0±0.10
321609	3.40±0.10	1.77±0.10	1.04±0.10	4.0±0.10	0.22±0.05	1.0±0.10

7-2.2 Tape Dimension / 12mm

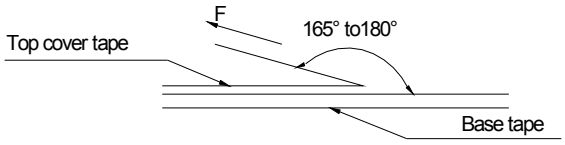


Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
451616	4.70±0.10	1.75±0.10	1.75±0.10	4.0±0.1	0.24±0.05	1.5±0.1
453215	4.70±0.10	3.45±0.10	1.60±0.10	8.0±0.1	0.24±0.05	1.5±0.1

7-3. Packaging Quantity

Chip Size	453215	451616	322513	321611	321609	201212	201209	160808	100505	060303
Chip / Reel	1000	2000	2500	3000	3000	2000	4000	4000	10000	15000
Inner box	4000	8000	12500	15000	15000	10000	20000	20000	50000	75000
Middle box	20000	40000	62500	75000	75000	50000	100000	100000	250000	375000
Carton	40000	80000	125000	150000	150000	100000	200000	200000	500000	750000

7-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

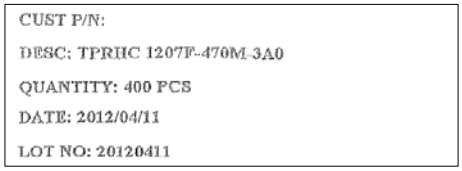
Room Temp. (℃)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

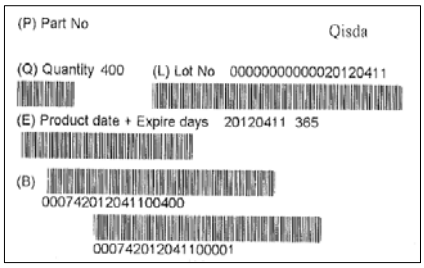
Application Notice

・Storage Conditions(component level)
To maintain the solder ability of terminal electrodes:
1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
2. Temperature and humidity conditions: Less than 40℃ and 60% RH.
3. Recommended products should be used within 12 months from the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

・Transportation
1.Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

標籤格式&條碼格式





8.Impedance vs Thermal Curves

